tehnotzka

https://tehnoteka.rs

Informacije o proizvodu (EN)

HP računar Pro 300 G6 (294S7EA)



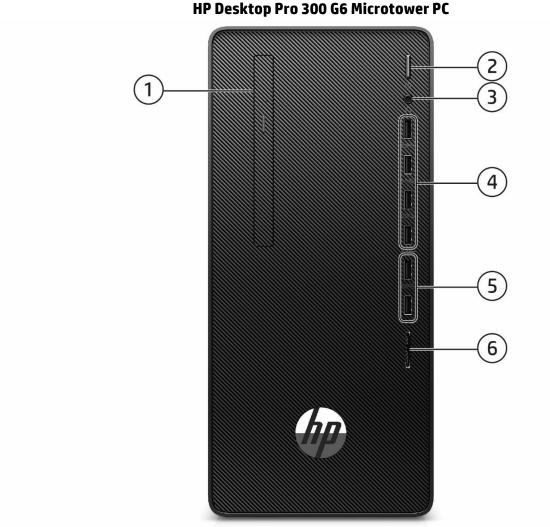


Tehnoteka je online destinacija za upoređivanje cena i karakteristika bele tehnike, potrošačke elektronike i IT uređaja kod trgovinskih lanaca i internet prodavnica u Srbiji. Naša stranica vam omogućava da istražite najnovije informacije, detaljne karakteristike i konkurentne cene proizvoda.

Posetite nas i uživajte u ekskluzivnom iskustvu pametne kupovine klikom na link:

https://tehnoteka.rs/p/hp-racunar-pro-300-g6-294s7ea-akcija-cena/

Overview



Front

- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (4) SuperSpeed USB 5Gbps port¹
- 5. (2) SuperSpeed USB 10Gbps port¹
- 6. SD Card Reader (Optional)

<u>Not Shown</u>

- Slots (1) PCI Express x16
 - PCI Express x1
 - (1) M.2 for WLAN
 - (1) M.2 2242/2280 storage
- Bays (1) 3.5" or 2.5" internal HDD bay
 - (1) 3.5" or 2.5" internal HDD bay (share bay with caddy)
 - (1) 9.5mm internal optical drive bay

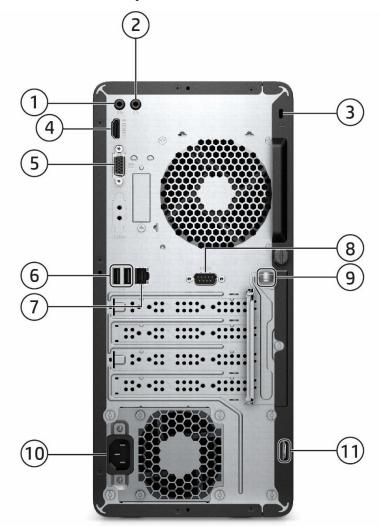
1. SuperSpeed USB 5Gbps signaling rate = USB 3.2 Gen1. SuperSpeed USB 10 Gbps signaling rate = USB 3.2 Gen2.



Not all configuration components are available in all regions/countries. c06953090 — DA 16787 — Worldwide — Version 5 — February 2, 2023

Overview

HP Desktop Pro 300 G6 Microtower PC



<u>Back</u>

- 1. Audio Line out
- 2. Audio Line in
- 3. Standard lock slot
- 4. HDMI Port
- 5. VGA Port
- 6. Connector (2) USB 2.0 port

<u>Not Shown</u>

(1) PS/2 Port (Optional)

- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4 Serial Port (Optional via PCIex1 slot)²
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)

- 7. RJ-45 Network
- 8. Serial Port (Optional)
- 9. Integrated accessories cable lock
- 10. Power Cord Connector¹
- 11. Padlock Loop

- 1. Power cord connector will be in different position, depends on which power supply configured.
- 2. Available in select countries only.



Standard Features and Configurable Modules

AT A GLANCE

- Windows 10 Pro, Windows 10 Home or FreeDOS
- Intel[®] H470 chipset supporting Intel[®] 10th processors featuring Intel[®] UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11ac (1x1) Wi-Fi[®] and Bluetooth[®] 4.2 Combo
- Up to 64GB DDR4- 2933 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (either dTPM or fTPM)¹
- Supports both Hard Disk Drives and M.2 PCIe NVMe Solid State Drives
- Up to 10 USB Ports (including native 4 SuperSpeed USB 5Gbps ports and 2 SuperSpeed USB 10Gbps³ and 2 USB 2.0 ports)
- 180W/310W 90% HE power supply
- Security cable lock supported (sold separately)
- Intrusion sensor supported (Optional)
- Optional HP Care Services available; terms and conditions vary by country; certain restrictions and exclusions apply²

1. TPM feature will be supported on machine pre-configured with FreeDOS, and will be default set as enabled in BIOS setup menu if the machine is dTPM, but will be default set as disabled in BIOS setup menu if the machine is fTPM.

2. HP Care Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

3. SuperSpeed USB 10Gbps signaling rate = USB 3.2 Gen2. SuperSpeed USB 5Gbps signaling rate = USB 3.2 Gen1

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Standard Features and Configurable Modules

PRODUCT NAME

HP Desktop Pro 300 G6 Microtower PC

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64 ¹
	Windows 10 Home 64 ¹
Pre-installed (other)	FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/

PROCESSORS

Intel[®] Celeron[®] Processors^{2,3}

CPU Intel Celeron G5905 Dual Core 3.4GHz 2666MHz 58W (3.4GHz, 2MB cache, 2 cores)

Intel[®] Pentium[®] Processors^{2,3}

CPU Intel Pentium Gold G6400 Dual Core 4.0GHz 2666MHz 58W (4.0GHz, 4MB cache, 2 cores) CPU Intel Pentium Gold G6600 Dual Core 4.2GHz 2666MHz 58W (4.2GHz, 4MB cache, 2 cores)

Intel 10th Processors

Intel® Core™ i3^{2,3} CPU Intel Core i3-10100 4C 3.6GHz 2666MHz 65W (3.6GHz, turbo up to 4.3GHz, 6MB cache, 4 cores)

Intel[®] Core[™] i5^{2,3}

CPU Intel Core i5-10400 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.0GHz, 12MB cache, 6 cores) CPU Intel Core i5-10500 6C 3.1GHz 2666MHz 65W (3.1GHz, turbo up to 4.2GHz, 12MB cache, 6 cores)

Intel[®] Core[™] i7^{2,3}

CPU Intel Core i7-10700 8C 2.9GHz 2933MHz 65W (2.9GHz, Up to 4.8GHz with Intel® Turbo Boost⁴, 16MB cache, 8 cores)

2.Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel 8th or 9th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

3. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance. 4. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information. ***NOTE:** Only available on selected region.

CHIPSET

Intel® H470



GRAPHICS

Integrated^{4,5}

Intel® UHD Graphics 630 (integrated on 10th Core i processors and Pentium Gold G6600) Intel® UHD Graphics 610 (integrated on Pentium Gold G6400 and Celeron)

Discrete Graphics

AMD Radeon™ R7 430 2GB GFX AMD Radeon™ RX550X 4GB GFX AMD Radeon™ 520 1GB GFX

4. HD content required to view HD images.

5. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

***NOTE:** Available in select countries only.

MEMORY⁶

Form Factor	Туре	Maximum	# of Slots
Microtower	DDR4 2933 (Transfer rates up to 2933 MT/s) DDR4 2666 (Transfer rates up to 2666 MT/s)	64 GB capacity	2 DIMM
4GB DDR4-2933 UD	IMM NECC (1x4GB)		
8GB DDR4-2933 UD	IMM NECC (1×8GB)		
8GB DDR4-2933 UD	IMM NECC (2x4GB)		
16GB DDR4-2933 U	DIMM NECC (2x8GB)		
16GB DDR4-2933 U	DIMM NECC (1x16GB)		
64GB DDR4-2933 U	DIMM NECC (2x32GB)		
4GB DDR4-2666 UD	IMM NECC (1x4GB)		
8GB DDR4-2666 UD	IMM NECC (1x8GB)		
8GB DDR4-2666 UD	IMM NECC (2x4GB)		
16GB DDR4-2666 U	DIMM NECC (1x16GB)		
16GB DDR4-2666 U	DIMM NECC (2x8GB)		
64GB DDR4-2666 U	DIMM NECC (2x32GB)		

6. Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate. **NOTE:** DDR4-2933 UDIMM is only available for 10th Gen i7 processor.

STORAGE

SATA3 - 3.5" or 2.5" HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive



Standard Features and Configurable Modules

Solid State Drives 128GB M.2 NVMe 256GB M.2 NVMe 512GB M.2 NVMe

SD Card Reader⁷ SD/SDHC/SDXC SD Card Reader

Intel Optane Memory⁷ SSD Intel 16GB 2280 Optane Memory

7. Optional per configuration

OPTICAL DISC DRIVES

DVD-ROM 9.5mm DVD-Writer⁸ 9.5mm

8. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing singlelayer DVD drives and players.

NETWORKING⁹

Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

Wi-Fi[®] and Bluetooth[®]

802.11ac (1x1) Wi-Fi[®] and Bluetooth[®] 4.2 Combo

9. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.



Standard Features and Configurable Modules

AUDIO / MULTIMEDIA

Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out (3.5mm)

KEYBOARDS AND POINTING DEVICES¹⁰

Keyboard

USB Business Slim Wired Keyboard HP USB Wired Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) Business Slim PS/2 Wired Keyboard (for machine configured with PS/2 port) No KB Option

Mouse

Antimicrobial USB Mouse (China) HP Optical USB Mouse Universal Wired USB Mouse USB Hardened Mouse (Specific region) HP PS/2 Mouse (for machine configured with PS/2 port) No Mouse Option

10. Keyboards and mouse are optional or add-on features.

PORTS

Front Slim-height Bay - supporting an optical disk drive (Optional) Power Button Combo jack, Headphone / Microphone SD Card Reader (Optional) (2) SuperSpeed USB 10Gbps port** (4) SuperSpeed USB 5Gbps port**

Not Shown

(1) PCI Express x16
(1) PCI Express x1
(1) M.2 for WLAN
(1) M.2 2242/2280 storage

Rear

Audio Line out Audio Line in HDMI Port



Standard Features and Configurable Modules

VGA Port

Serial Port (Optional on selected sku) 2nd Serial Port (Optional) Standard Lock Slot (2) USB 2.0 port (2) USB 2.0 port (Optional on selected sku) RJ-45 Network connector Power cord connector Padlock loop Integrated accessories cable lock

Not Shown

(1) PS/2 Port (Optional)
 (1) Parallel Port (Optional via PCIex1 slot)
 (1) 4x Serial port (Optional via PCIex1 slot)*
 (1) Internal Speaker (Optional)
 (1) Intrusion Sensor (Optional)

NOTE*: Available in select countries only. **NOTE**:** SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

BAYS

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" or 2.5" internal HDD or bay
- (1) 3.5 or 2.5" internal HDD bay (share bay with caddy)

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection McAfee* LiveSafe^{™ 12}

Productivity

Buy Office (sold separately) Dropbox¹³

ODD Playback sMedio True DVD for HP

Movies

Netflix¹⁴

App Stores and Content Purchasing Amazon¹⁴

HP Utilities and Support

HP Documentation HP JumpStarts HP Audio Switch¹⁵ **HP Support Assistant**

BTB

HP Setup Integrated OOBE

Hardware Enabling Drivers or software utility

HP System Event Utility

12. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 13. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.

14. Internet access required and not included. Apps sold separately.

15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.

***NOTE**: Available in Latin America countries only.

POWER SUPPLY¹⁶

180 W ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V 310 W SFF ENTL EPA90 (Gold) Full range 115V/230V 500 W EPA90 (Gold) Full range 115V/230V

16. All power supplies are not available in every region.



DIMENSIONS AND WEIGHT

Dimensions

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

Weight

10.4 lbs / 4.7 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
 enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5° to 35° C ¹⁷ Non-operating: -30° to 60° C ¹⁷
Relative Humidity	Operating: 5% to 90% (non-condensing at ambient) Non-operating: 5% to 90% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000 m Non-operating: 50000ft (15240 m)

17. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT^O Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".



Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	28.12W	28.27W	28.27W
Normal Operation (Long idle)	26.34W	26.51W	26.51W
Sleep	1.66W	1.67W	1.67W
Off	0.29W	0.30W	0.30W
	NOTE: Energy efficiency data listed model family. HP computers marke U.S. Environmental Protection Ager family does not offer ENERGY STAR for a typically configured PC feature Microsoft Windows® operating syst	d with the ENERGY STAR [®] Logo a ncy (EPA) ENERGY STAR [®] specific [®] compliant configurations, ther ng a hard disk drive, a high effici	are compliant with the applicable ations for computers. If a model n energy efficiency data listed is
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	96 BTU/hr	96 BTU/hr	96 BTU/hr
Normal Operation (Long idle)	90 BTU/hr	90 BTU/hr	90 BTU/hr
Sleep	6 BTU/hr	6 BTU/hr	6 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr
Declared Noise Emissions (in accordance with	attained for one hour. Sound Power Sound Pressure (LwAd, bels) (LpAm, decibels)		
ISO 7779 and ISO 9296) Typically Configured – Idle	3.7		24.7
Fixed Disk – Random writes	4.1		29.8
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "3" years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	 This product is in compliance with 2011/65/EC. This HP product is designed to cor Directive – 2002/96/EC. This product is in compliance with and Toxic Enforcement Act of 1986 	nply with the Waste Electrical an California Proposition 65 (State	d Electronic Equipment (WEEE)



	 This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <silver> level, see www.epeat.net</silver> Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 28.2% post-consumer recycled plastic (by wt.) This product is 91.7% recycle-able when properly disposed of at end of life. 		
Packaging Materials	External:	PAPER/Paperboard	1220 g
	Internal:	PAPER/Molded Pulp	520 g
		PLASTIC/Polyethylene low density - LDPE	53 g
Material Usage	PLASTIC/Polyethylene low density - LDPE 53 g This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos • Certain Azo Colorants • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (pCT) • Polyuntarily removed from most applications. • Radioactive Substances		
Packaging Usage End-of-life	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 		
Management and Recycling	recycle your sales office. manner. The EU WEEI each produc is posted on may be used integrate an	product, please go to: http://www.hp.com/go/reu Products returned to HP will be recycled, recovere t directive (2002/95/EC) requires manufacturers to t type for use by treatment facilities. This informa the Hewlett Packard web site at: http://www.hp.c by recyclers and other WEEE treatment facilities a d re-sell HP equipment. nship Report	ise-recycle or contact your nearest HP ed or disposed of in a responsible o provide treatment information for tion (product disassembly instructions) om/go/recyclers. These instructions



http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_ Certificate.pdf
and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty 1: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day 2 service for parts and labor and complimentary limited technical support.3 Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.4 To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. **NOTE 3:** Technical support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

GRAPHICS

DisplayPort™	Multimode capable; supports HDCP, DisplayPort™ Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)
Memory	Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Graphics Memory	Windows 10: >4 GB
Maximum Color Depth	32 bits/pixel
Graphics/Video API Support	10 th Generation Intel [®] Core Processors, Pentium and Celeron
	With Intel® UHD Graphics 630
	Pentium [®] and Celeron [®]
	With Intel [®] UHD Graphics 610
Supported Display Resolutions	Max. Resolution (VGA) 2048 x 1536@60Hz
and Refresh Rates	Max. Resolution (HDMI) 4096 x 2160@60Hz

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort[™] connector.

AMD Radeon™ R7 430 2GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

Technical Specifications - Graphics

AMD® Radeon™ RX550X 4 GB FH PCIe x16

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

AMD Radeon™ 520 1GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1GB(32-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket



Technical Specifications - Storage

STORAGE¹

HP 2 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6Gb/s NCQ
Buffer Size	64 MB
Logical Blocks	3,907,029,168
Seek Time	Read: <8.5 ms Write: <9.5 ms
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	32° to 140° F (0° to 60° C)

1 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

500 GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity Rotational Speed Interface Buffer Size Logical Blocks	500 GB 7,200 rpm Serial ATA 3.0 (6.0 Gb/s) 32 MB 1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height Width	1 in/2.54 cm Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)



Technical Specifications - Storage

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature Features	0° to 70°C (32° to 158°F) [ambient temp] APST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216

Technical Specifications - Storage

Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

500 GB 7200RPM 2.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)



Technical Specifications - Storage

Operating Temperature 41° to 131° F (5° to 55° C)

1TB 7200RPM 2.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

1. For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software. Storage DriveLock does not work with Self Encrypting or Optane based storage.



Technical Specifications – Optical Drives

OPTICAL DISC DRIVES

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height	9.5 mm height	9.5 mm height		
Orientation	Either horizontal or vertical			
Interface type	SATA/ATAPI			
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard		
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel			
Weight (max)	0.31 lb (140 q)			
Read Speeds	DVD-R DL DVD+R DVD+RW DVD+R DL DVD-R DVD-RW CD-R CD-RW DVD-RW, DVD+RW DVD-RW, DVD+R DL DVD-R DL, DVD+R DL DVD+R, DVD-R DVD-ROM DL, DVD-ROM CD-ROM, CD-R CD-RW	Up to 6X Up to 8X Up to 8X Up to 6X Up to 6X Up to 6X Up to 24X Up to 10X Up to 8X Up to 8X Up to 8X Up to 8X Up to 8X Up to 8X Up to 24X Up to 24X Up to 24X		
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)			
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)			
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)			

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard	
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 g)	
Read Speeds	DVD-R DL DVD+R DVD+RW DVD+R DL DVD-R DVD-RW CD-R	Up to 6X Up to 8X Up to 8X Up to 6X Up to 8X Up to 6X Up to 24X



Technical Specifications – Optical Drives

	CD-RW DVD-RW, DVD+RW DVD-R DL, DVD+R DL DVD+R, DVD-R DVD-ROM DL, DVD-ROM CD-ROM, CD-R CD-RW	Up to 10X Up to 8X Up to 8X Up to 8X Up to 8X Up to 24X Up to 24X	
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)		
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)		
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)		



Technical Specifications – Networking

NETWORKING

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
		100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
		1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
		Auto-Negotiation (Automatic Speed Selection)
		Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power	ACPI compliant – multiple power modes
	Management	Situation-sensitive features reduce power consumption
		Advanced link down power saving for reducing link down power consumption
	Performance	TCP/IP/UDP Checksum Offload (configurable)
	Features	Protocol Offload (ARP & NS)
		Large send offload and Giant send offload
		Receiving Side Scaling
		Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up
		Frame); Wake-on-LAN from off (Magic Packet only)
		PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause
		30)
		Comprehensive diagnostic and configuration software suite
		Virtual Cable Doctor for Ethernet cable status
	Interface	PCIe + SMBus
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

Realtek 802.11ac (1x1)	Wi-Fi [®] and Bluetooth [®] 4.2 Combo *

Wireless LAN Standards ¹	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac 1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.		
Interoperability	Wi-Fi [®] certified modules		
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz NOTE: The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.	
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz	



Technical Specifications – Networking

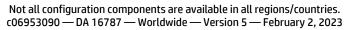
Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ²	IEEE and 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	2 Check latest software/driver release for updates on supported security features.
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	 802.11b : +14dBm minimum 802.11g : +12dBm minimum 802.11a : +12dBm minimum 802.11n HT20(2.4GHz) : +12dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +10dBm minimum 802.11n HT40(5GHz) : +10dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 3. Maximum output power may vary by country according to local regulations.
Power Consumption	•Transmit mode2.0 W •Receive mode1.6 W •Idle mode (PSP)180 mW(WLAN Associated) •Idle mode50 mW(WLAN unassociated) •Connected Standby 10mW •Radio disabled8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode



(III)

Technical Specifications – Networking

Receiver Sensitivity ⁴	802.11b, 1Mbps : -93.5dBm maximum			
······	802.11b, 11Mbps : -84dBm maximum			
	802.11a/g, 6Mbps : -86dBm maximum			
	802.11a/g, 54Mbps : -72dBm maximum			
	802.11n, MCS07 : -67dBm maximum			
	802.11n, MCS15 : -64dBm maximum			
	802.11ac, MCS0 : -84dBm maximum			
	802.11ac, MCS9 : -59dBm maximum			
	4 Receiver sensitivity is measured at a packe error rate of 10% for 802.11a/g (OFDM modu	t error rate of 8% for 802.11b (CKK modulation) and a packet ılation).		
Antenna type	Two embedded dual band 2.4/5 GHz ante	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications		
Form Factors	PCI-Express M.2 MiniCard			
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm			
Weight	Туре 2230 : 2.8g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating: 14° to 158° F (-10° to 70° C) Non-operating: -40° to 176° F (-40° to 80° C)			
Humidity	Operating:10% to 90% (non-condensing)Non-operating:5% to 95% (non-condensing)			
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)			
LED Activity	LED Amber – Radio OFF; LED White – Radi	io ON		
HP Integrated Module with Blue	tooth 4.0/4.1/4.2 Wireless Technology			
Bluetooth [®] Specification	4.0/4.1/4.2 Compliant			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)			
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps			
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels			
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)			
Transmit Power	The Bluetooth [®] component shall operate as a Class II Bluetooth [®] device with a maximum transmit power of + 4 dBm for BR and EDR.			



Technical Specifications – Networking

Receiver Sensitivity Legacy				
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW			
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)			
Electrical Interface	USB 2.0 compliant			
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software			
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark			
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support			
Certifications Bluetooth [®] Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)			

Technical Specifications - Audio

HIGH DEFINITION AUDIO

Туре	Integrated
HD Stereo Codec	Realtek ALC3601
Audio I/O Ports	Front side Combo jack for supporting CTIA, Rear side Line-in / Line-out / Mic-in jacks
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
HD Audio Codec	Realtek ALC3601
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/ 48 K / 96K / 192K Hz for DAC and 44.1K / 48K / 96K / 192K Hz for ADC
Wavetable Syntheses	Yes
Analog Audio	Yes
# of Channels on Line-Out	Stereo
Internal Speaker	Yes
External Speaker Jack*	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.
NOTE*: Optional	

Technical Specifications - Power

POWER SUPPLY

Operating Voltage Range	90 – 264 VAC
Rated Voltage Range	100-240V AC
Rated Line Frequency	50/60 HZ
Operating Line Frequency	47 – 63 Hz
Rated Input Current	180W : <2.3A; 310W: <4A 500W: <6A
Rated Input Current with Energy Efficient* Power Supply	180W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V); 310W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V) 500W active PFC 87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V)
DC Output	+12.1V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	180W/310W: 70*25mm (linear type) 500W: 70*25mm (PWM type)

Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS

Chassis (W x D x H)	6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm) (w/ bezel)	
System Volume	15.1 L	
System Weight*	10.4 lbs / 4.7 kg	
Packaged (H x W x D)	11.3 x 15.75 x 19.65 in 287 x 400 x 499 mm	
Shipping Weight	17.64lb / 8 kg	
Palletization Profile	6 units per layer 7layer max 42 per pallet Footprint -85.31x39.37x47.24 in (2167 x 1000 x1200 mm)	



After-Market Options (availability may vary by region)

AFTERMARKET OPTIONS

Туре	Description	Part #
Memory	HP 4GB DDR4-2666 DIMM	3TK85AA
	HP 8GB DDR4-2666 DIMM	3TK87AA
	HP 16GB DDR4-2666 DIMM	ЗТК8ЗАА
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	NVIDIA® GT 730 2GB DP Card	Z9H51AA
· ·	AMD Radeon™ R7 430 2GB 2DP Card	5JW82AA
Security	HP Business PC Security Lock V3 Kit	
	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP HDMI Standard Cable Kit	T6F94AA
	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	N1M40AA
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Grey v2 Mouse	Z9H74AA
	HP USB Keyboard	QY776AA
	HP PS/2 Business Slim Keyboard	N3R86AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Backlit USB Mechanical Keyboard	4RV35AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	
	HP S101 Speaker bar	5UU40AA

Change Log

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Date of change:	Version History:	Change	Description of change:
November 3, 2020	From v1 to v2	Update	Rear call outs image and configuration changed. Disclaimer added and I7-10700 specs corrected in processors section.
January 25, 2021	From V2 to V3	Update	Front call outs disclaimers updated
June 16, 2022	From V3 to V4	Update	Environmental table certifications updated
February 2, 2023	From V4 to V5	Update	i3-10100 updated to 4.3GHz at Processors section
	From V5 to V6		



tehnotzka

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